

Title (en)
COMPONENTS WITH RELEASABLE LEADS

Title (de)
BAUTEILEN MIT LÖSBAREN LEITERN

Title (fr)
COMPOSANTS DOTES DE FILS DETACHABLES

Publication
EP 1059019 A4 20071017 (EN)

Application
EP 99905891 A 19990209

Priority
• US 9902748 W 19990209
• US 2075098 A 19980209
• US 19537198 A 19981118
• US 22566999 A 19990105

Abstract (en)
[origin: WO9940761A1] A microelectronic component is made by providing a starting structure having a dielectric layer (22) and leads on a surface of the dielectric layer. The dielectric layer is etched to partially detach the leads (24) from the dielectric layer, leaving a portion of each lead releasably connected to the dielectric layer. Ends of the leads (24) may be connected to contacts (52) on a microelectronic element (50), such as the contacts on a semiconductor chip or wafer, before the dielectric layer (22) is etched to partially detach the leads (24) from the dielectric layer. The lead is partially detached from the dielectric layer so that the dielectric layer can be broken or peeled away from the leads during the step of moving the microelectronic element (50) and dielectric layer (22) away from one another.

IPC 1-7
H05K 3/30; **H01R 9/09**

IPC 8 full level
H01L 21/48 (2006.01); **H01L 21/60** (2006.01); **H01L 23/13** (2006.01); **H01L 23/32** (2006.01); **H01L 23/48** (2006.01); **H01L 23/498** (2006.01); **H05K 3/32** (2006.01); **H05K 3/40** (2006.01)

CPC (source: EP KR)
H01L 21/4846 (2013.01 - EP); **H01L 23/13** (2013.01 - EP); **H01L 23/49811** (2013.01 - EP); **H01L 23/4985** (2013.01 - EP); **H01L 24/13** (2013.01 - EP); **H01L 24/72** (2013.01 - EP); **H05K 3/30** (2013.01 - KR); **H05K 3/4092** (2013.01 - EP); **H01L 24/81** (2013.01 - EP); **H01L 2223/6622** (2013.01 - EP); **H01L 2223/6627** (2013.01 - EP); **H01L 2224/81192** (2013.01 - EP); **H01L 2224/81801** (2013.01 - EP); **H01L 2924/0002** (2013.01 - EP); **H01L 2924/01005** (2013.01 - EP); **H01L 2924/01006** (2013.01 - EP); **H01L 2924/01027** (2013.01 - EP); **H01L 2924/01029** (2013.01 - EP); **H01L 2924/01033** (2013.01 - EP); **H01L 2924/01061** (2013.01 - EP); **H01L 2924/01078** (2013.01 - EP); **H01L 2924/01079** (2013.01 - EP); **H01L 2924/01082** (2013.01 - EP); **H01L 2924/01322** (2013.01 - EP); **H01L 2924/1903** (2013.01 - EP); **H01L 2924/3011** (2013.01 - EP)

Citation (search report)
• [DX] WO 9403036 A1 19940203 - TESSERA INC [US], et al
• [DA] US 5518964 A 19960521 - DISTEFANO THOMAS H [US], et al
• [A] US 5086337 A 19920204 - NORO TAKANOBU [JP], et al
• See references of WO 9940761A1

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
WO 9940761 A1 19990812; AU 2594399 A 19990823; EP 1059019 A1 20001213; EP 1059019 A4 20071017; JP 2002503038 A 20020129; KR 100721725 B1 20070528; KR 20010040775 A 20010515

DOCDB simple family (application)
US 9902748 W 19990209; AU 2594399 A 19990209; EP 99905891 A 19990209; JP 2000531040 A 19990209; KR 20007008667 A 20000808